

FWF12511 Wafer Series

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Wafer Connector FWF12511 Series

This specification covers the Wafer Connector FWF12511 Series

2. Connector Dimensions

Refer to the drawing.

3. Material

Housing:PA9T UL94V-0

Color: White

Contacts Terminal:Brass

Plating:Gold Plated

4. Accommodated P.C.B Layout

Refer to the drawing.

5. Rating

Operating Voltage(Max.) 125V AC/DC

Current Rating(Max.) 1.0A DC/AC

Operating Temperature -25°C -- +85°C(Including terminal temperature rese)



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6. Performance

Репогтапсе		Electrical Performance			
Contact Resistance	20mΩ Max	Mate connectors,Measure by dry circuit.20mV Max. 10mA			
Insulation Resistance	100MΩ Min	Mate applicable connectors and apply 500V DC between adjacent terminal or ground.			
Dielectric Strength	No breakdown and flashover	Mate applicable connectors, apply 250V AC(rms) for 1 minute between adjacent terminal or ground.			
	N	lechanical Performance			
Insertion force	Circuit No. x 0.25kgf (Max)	Insert the line into the connector at the speed rate of 25±3mm/minute.			
Withdrawal force	Circuit No. x 0.07kgf (Min)	Apply axial pull out force at the speed rate of 25±3mm/minute on the line assembled in the connector.			
Terminal retention force	0.8kgf Min	Apply axial pull out force at the speed rate of 25±3mm/minute on the terminal assembled in the connector.			
	Environr	nental Performance and otl	ners		
Heat Resistance	Mated connector shall be placed in a oven		Appearance	No Damage	
		for 96±4 hours at +85±3°C (Based upon JIS C5402 7.8)		40mΩ Max	
Cold Resistance	Mated connector shall be placed in a temperature chamber for 96±4 hours at -25± 3°C (Based upon JIS C5402 7.9)		Appearance	No Damage	
			Contact Resistance	40mΩ Max	
	Mated connector shall be placed in a humidity chamber on the following conditions . Temperature:40±2°C Relative humidity:90~95% Duration:96 Hours (Based upon MIL-STD-202 Method 103 conditions A)		Appearance	No Damage	
Humidity			Contact Resistance	40mΩ Max	
			Dielectric strength	No Breakdown	

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Temperature Cycling	Mated connector shall be set to temperature cycling for 5 cycles of which 1 cycle consists	Appearance	No Damage
	of: 125°C3minutes 2.+85°C30minutes 325°C3minutes 4.+65°C30minutes (Based upon JIS C5402 7.2)	Contact Resistance	40mΩ Max
		Dielectric strength	No Breakdown
Salt Spray	Mated connector shall be placed in a salt spray chamber on the following conditions. Salt solution density: 5±1%	Appearance	No Damage
	Temperature: 35±2°C Duration: 12 Hours	Contact Resistance	40mΩ Max
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Solderability	Tip of solder tails and fitting nails into the molten solder (held at $250\pm5^{\circ}$ C) up to 0.1mm form the bottom of the housing for 3 ±0.5 seconds.	Solder Wetting	95% of immersed area must show no voids nor pin holes
Resistance to Soldering Heat	Mated connector shall be dipped on solder bath for 5±0.5sec temperature :265±5°C	Appearance	No Damage

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